

The MBI6651 Application Note

Overview

The MBI6651 is a constant current, step-down DC/DC converter with high efficiency, and is designed to drive high power LED in constant current. The Hysteretic PFM control scheme enhances the efficiency at light load condition. The output current can be programmed by an external resistor, and the DIM pin provides another method to adjust the output current by connecting a PWM signal. The embedded peak current limit protects LED from being damaged by large current. The MBI6651 also features Under Voltage Lock Out (UVLO), Over Temperature Protection, Open Circuit Protection and Short Circuit Protection to protect IC from being damaged.

With only 4 external components required to achieve power conversion, the MBI6651's built-in MOSFET allows the use in space sensitive application. MBI6651 provides three different packages including TO252-5, SOT23-6 and MSOP8. The TO252-5 and MSOP8 packages offer a thermal pad to enhance the heat dissipation. And tiny package, SOT23-6, saves space in application.

Hysteretic PFM Control Scheme

The key feature of the MBI6651 is its hysteretic pulse-frequency-modulation (PFM) control scheme with high side current limit. When the power is on, V_{SEN} is lower than V_H (1.15 times of V_{SEN}), which causes the internal MOSFET of the MBI6651 to turn on and V_{SEN} increase with I_L . Until V_{SEN} is equal to V_H , the MOSFET turns off, and V_{SEN} decreases with I_L . When V_{SEN} decreases and is down to V_L (0.85 times of V_{SEN}), the internal MOSFET turns on again, and repeat the actions above. However, the inductor current will always work on Continuous Current Mode (CCM) due to the character of the Hysteretic PFM control. This is helpful in terms of reducing the LED ripple current. Figure 1 below demonstrates the application circuit of the MBI6651, and Figure 2 shows the waveform of the Hysteretic PFM control scheme.

The switching frequency of this control scheme varies according to the output loading; the heavier the loading, the lower switching frequency will result. When it is under the same loading condition, the larger inductance will result the lower switching frequency. The lowest switching frequency is limited to 40 kHz so to avoid audio noise.

The high side current limit allows users to choose a smaller size and offers lower power consumption resistor than that in low side current limit unit. As a result, it is helpful in terms of space-saving and cost effectiveness considerations.

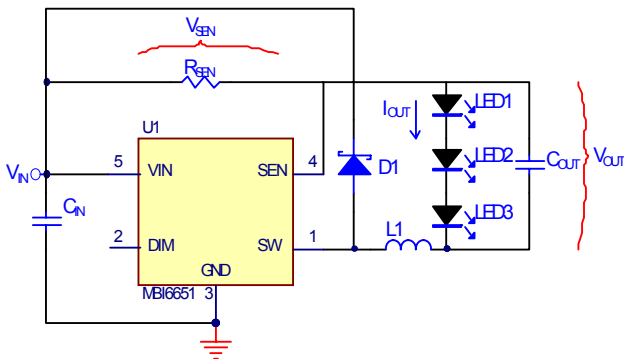


Figure 1. Application circuit of MBI6651

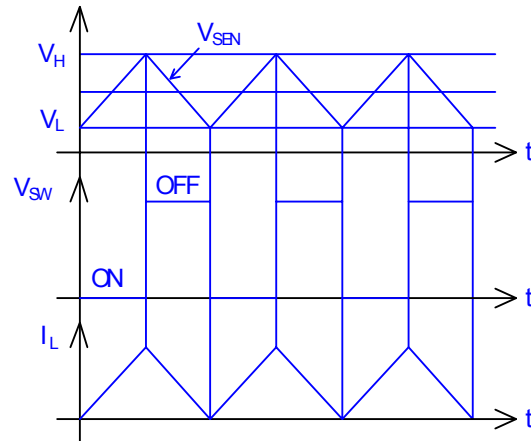


Figure 2. Waveform of hysteretic PFM control scheme

Under Voltage Lock Out (UVLO)

The typical voltage of the MBI6651 UVLO is 8V. If the input voltage is lower than 8V, the internal MOSFET of the MBI6651 is then off, which prevents current from going through. Also, the MBI6651 features a hysteretic of UVLO when IC is working. If the input voltage is down to 7.8V again, the internal MOSFET of MBI6651 turns off.

Peak Current Limit

For normal operation, a dropout voltage between input and output voltage is desired. ***As the input voltage becomes lower than the minimum input voltage—which is the sum of the dropout voltages on each external components and the total forward voltage of the cascaded LEDs, the internal MOSFET of the MBI6651 will always turn on, and the maximum LED current is limited to 1.15 times of the expect current.*** On the contrary, if the input voltage is larger than the minimum input voltage, or if the total forward voltage of the cascaded LEDs decreases due to LED's rising temperature, the output current will recover to the preset one.

Dimming

The LED current can be adjusted by connecting a PWM signal to DIM pin of the MBI6651. When a low level signal (lower than 0.5V) appears at the DIM pin, the internal MOSFET turns off and shuts the LED current, and vice versa. The high voltage of DIM pin is 3.5V. The larger duty cycle of PWM signal will result higher LED current. To avoid the audio noise caused by low PWM frequency, a smaller inductor value can be considered, but it is a trade-off with the line/load regulation. For linear dimming, the maximum frequency applies to DIM pin is 1kHz.

Open Circuit Protection

The MBI6651 has a built-in open circuit protection. The internal MOSFET stops switching and remains at turn off state. The LED current is zero when LED is opened.

Short Circuit Protection

The MBI6651 offers a short circuit protection. As LED is short, the output voltage will drop to zero, but the internal MOSFET will keep on switching and the output current will be preset value. In multi-LED in cascaded application, if one or more than one LEDs are short, the output voltage across the LEDs will be decreased, and yet the LED current is still available to maintain its preset value.

Over Temperature Protection

The MBI6651 offers an over temperature protection, and the protect temperature is 165 °C. As junction temperature exceeds over 165 °C, the internal MOSFET will turn off and shut down the LED current. Thus, the junction temperature will start to decrease. As the junction temperature is below 135 °C, the internal MOSFET will turn on again and recover switching.

Design Consideration

Switching Frequency

To achieve better output current accuracy, the switching frequency should be determined by minimum on/off time of SW waveform. For example, if the duty cycle of MBI6651 is larger than 0.5, then the switching frequency should be determined by the minimum off time, and vice versa. Thus the switching frequency of MBI6651 is

$$f_{SW} = \frac{1}{T_S} = \frac{1}{\frac{T_{OFF,min}}{(1-D)}}, \text{ when the duty cycle is larger than 0.5} \quad (1)$$

$$\text{or } f_{SW} = \frac{1}{T_S} = \frac{1}{\frac{T_{ON,min}}{D}}, \text{ when the duty cycle is smaller than 0.5.} \quad (2)$$

The switching frequency is related to efficiency (better at low frequency), components size/cost (smaller/cheaper at high frequency), and the amplitude of output ripple voltage and current (smaller at high frequency). The slower switching frequency comes from the large value of inductor. On many applications, the sensitivity of EMI limits the switching frequency of MBI6651. The switching frequency can be ranged from 40kHz to 1MHz.

LED Ripple Current

A LED constant current driver, such as MBI6651, is designed to control the current through the cascaded LED, but the voltage across it. Higher LED ripple current allows the use of smaller inductance, smaller output capacitance and even without an output capacitor. The advantages of higher LED ripple current are to minimize PCB size and reduce cost because of no output capacitor. Lower LED ripple current requires larger inductance, and output capacitor. The advantages of lower LED ripple current are to extend LED life time and to reduce heating of LED. The recommended ripple current is from 5% to 20% of normal LED current.

Component Selection

Output Current Setting

The output current can be programmed by an external resistor, the relationship between I_{OUT} and R_{SEN} is

$$R_{SEN} = (V_{SEN} / I_{OUT}) \quad (3)$$

where R_{SEN} is current sense resistor, which is connected between VIN and SEN pin of the MBI6651, 1% tolerance is recommended for better output current accuracy, and V_{SEN} is the voltage across R_{SEN} . The sustaining power dissipation on R_{SEN} , P_{RSEN} , is

$$P_{RSEN} = (V_{SEN}^2 / R_{SEN}) \quad (4)$$

Inductor Selection

The inductance is determined by two factors: the switching frequency and the inductor ripple current. The calculation of the inductance, L_1 , can be described as

$$L_1 > (V_{IN} - V_{OUT} - V_{SEN} - (R_{ds(on)} \times I_{OUT})) \times \frac{D}{f_{SW} \times \Delta I_L} \quad (5)$$

where

$R_{ds(on)}$ is the on-resistor of internal MOSFET of MBI6651. The typical is 0.45Ω at $12V_{IN}$.

D is the duty cycle of MBI6651, $D = V_{OUT} / V_{IN}$.

f_{SW} is the switching frequency of MBI6651.

I_L is the ripple current of inductor, $I_L = (1.15 \times I_{OUT}) - (0.85 \times I_{OUT}) = 0.3 \times I_{OUT}$.

When selecting an inductor, the inductance is not the only factor to affect the performance of module, but the saturation current also needs to be considered. In general, it is recommended to choose an inductor with 1.5 times of LED current as the saturation current. Also, the larger inductance gains the better line/load regulation and efficiency. However, when at the same inductor size, the inductance and saturation current becomes a trade-off. An inductor with shield is recommended to reduce the EMI interference, but this is another trade-off with heat dissipation.

Schottky Diode Selection

The MBI6651 needs a flywheel diode, D1, to carry the inductor current when the MOSFET is off. The recommended flywheel diode is schottky diode with low forward voltage for better efficiency. Two factors determine the selection of schottky diode. One is the maximum reverse voltage, and the recommended rated voltage of the reverse voltage is at least 1.5 times of input voltage. The other is the maximum forward current, which works when the MOSFET is off. The recommended forward current is 1.5 times of output current. Since the switching characteristics of schottky diode degrades with the rising temperature, the recommended operating temperature is 85 to prevent MBI6651 from being damaged by large leakage current, which caused by schottky diode.

Minimum Input Voltage

The minimum input voltage is the sum of the voltage drops on R_{SEN} , R_S , DCR of L1, $R_{ds(on)}$ of internal MOSFET and the total forward voltage of LEDs. The dynamic resistance of LED, R_S , is the inverse of the slope in linear forward voltage model for LED. This electrical characteristic can be provided by LED manufacturers. **As the input voltage is smaller than minimum input voltage, which is pointed out by MBI6651 Design Tool, the output current will be larger than the preset output current, and is limited to 1.15 times of preset one.** The equivalent impedance of the MBI6651 application circuit is shown as in Figure 3. To calculate these voltage drops, the peak LED current must be defined first. As previously mentioned, the peak current is 1.15 times of the preset current, and then the voltage drops on each component can be calculated as below

$$V_{R_{SEN}} = V_{SEN} \times 1.15 \quad (6)$$

$$V_{R_S} = R_S \times I_{OUT} \times 1.15 \times n, \text{ where } n \text{ is the amount of LED.} \quad (7)$$

$$V_{MOSFET} = R_{ds(on)} \times I_{OUT} \times 1.15 \quad (8)$$

$$V_{L1} = DCR \times I_{OUT} \times 1.15 \quad (9)$$

Thus, the minimum input voltage ($V_{IN, MIN}$) can be defined as

$$V_{IN, MIN} = V_{R_{SEN}} + V_{R_S} + V_{MOSFET} + V_{L1} + V_{F, LED} \quad (10)$$

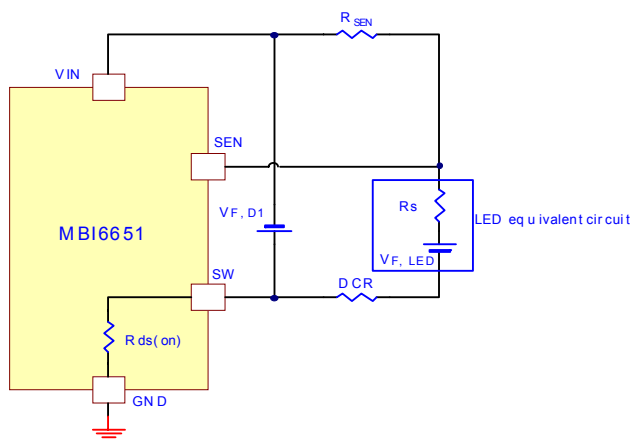


Figure 3. The equivalent impedance of MBI6651 application circuit

Input Capacitor Selection

The input capacitor, C_{IN} , can supply pulses of current for the MBI6651 when the MOSFET is on, and C_{IN} is charged by input voltage when the MOSFET is off. As the input voltage is lower than the tolerable input voltage, the internal MOSFET of the MBI6651 becomes constantly “on”, and the LED current is limited to 1.15 times of normal current. The recommended value of input capacitor is 10uF for stabilizing the lighting system. The rated voltage of input capacitor should be at least 1.5 times of input voltage.

For system stability, place the C_{IN} to the V_{IN} pin of MBI6651 as close as possible is recommended. However, the PCB size might limit this requirement. Therefore, to avoid the noise interference, a bypass capacitor, whose capacitance range is from 0.1uF to 1uF and material is ceramic, parallel with the V_{IN} and GND pins of MBI6651 is recommended. The rated voltage of bypass capacitor should be at least 1.5times of input voltage.

The rated voltage and capacitance are not the only concern when selecting capacitors, but also the maximum ripple current. If the specification of maximum ripple current is smaller than the produced, the capacitor might be damaged and furthermore damage IC. In general, the ripple current is related to the inductor ripple current. The specification of maximum ripple current of capacitor should be larger than 1.3 times of the inductor ripple current.

A tantalum or ceramic capacitor can be used as an input capacitor. The advantages of tantalum capacitor are high capacitance and low ESR. The advantages of ceramic capacitor are high frequency characteristic, small size and low cost. Compare with the tantalum capacitor, the ceramic capacitor features the lower ESR, so it is not recommended to use in hot plugging application. Users can choice an appropriate one for applications.

Output Capacitor Selection (Optional)

For reducing LED ripple current, a capacitor parallels with the cascaded LED is recommended. Proportionally, the higher capacitor value results the lower LED ripple current. Normally, a 10uF output capacitor with low ESR is desired, and the recommended rated voltage of the output capacitor is 1.5 times of total LED forward voltage. Without this paralleled capacitor, the LED ripple current is equal to the inductor current, 0.3 times of LED current. Note that the output capacitor can neither affect the switching frequency nor efficiency. The material of output capacitor can be selected to tantalum or ceramic unit. For maximum stability over temperature, the output/input capacitor with X7R or X5R dielectric is recommended. A ceramic capacitor with Y5V dielectric is not recommended in this application due to bad temperature compensation.

Estimated Efficiency

To estimate the efficiency, the power consumption on each current carrying element must be calculated and summed up. The efficiency (η) can be described as

$$\eta = \frac{P_{OUT}}{P_{OUT} + P_{LOSS}} \quad (11)$$

where

P_{OUT} is the power consumption of LED. The calculation is

$$P_{OUT} = V_{OUT} \times I_{OUT} \quad (12)$$

The power loss (P_{LOSS}) in stet-down DC/DC converter includes

$$P_{LOSS} = P_C + P_{SW} + P_{IC} + P_L + P_{D1} + P_{RSEN} \quad (13)$$

where

P_C is conduction loss during the internal MOSFET turns on, $P_C = I_{OUT}^2 \times R_{ds(on)} \times D$.

P_{SW} is the switching loss of the MOSFET during switching, $P_{SW} = V_{IN} \times I_{OUT} \times (t_r + t_f) \times f_{SW}$. t_r and t_f are the rising and falling times of the switch signal.

P_{IC} is the power consumption of MBI6651, $P_{IC} = I_{DD} \times V_{IN}$. I_{DD} is the supply current of MBI6651, normally is 1mA.

P_L is the inductor loss caused by the DC resistance (DCR) of inductor, $P_L = I_{OUT}^2 \times DCR$.

P_{D1} is the power loss of schottky diode, $P_{D1} = V_{F,D1} \times I_{OUT} \times (1-D)$, $V_{F,D1}$ is the forward voltage of schottky diode.

P_{RSEN} is the power loss on R_{SEN} , $P_{RSEN} = V_{SEN} \times I_{OUT}$.

Estimated Junction Temperature

The power losses will cause temperature rising on the MBI6651 body. When the junction temperature (T_J) reaches 165 °C, the MBI6651 will enter thermal protection model and shut the LED current off. Thus, it's important for designers to recognize the relationship between power losses and rising temperature. The relationship can be described as

$$T_J = T_A + P_{LOSS, IC} \times R_{th, JA} \quad (14)$$

where

T_A is the ambient temperature.

$P_{LOSS, IC}$ is the power loss in MBI6651, $P_{LOSS, IC} = P_C + P_{SW} + P_{IC}$.

$R_{th, JA}$ is thermal resistor of MBI6651 from junction to ambient.

Design Example 1

For lighting 2 pieces of high power white LEDs, the forward voltage of LED is 3.72V/pcs. The desired LED current is 350mA, input voltage is 12V. Please calculate the required components. (The package of MBI6651 is MOSP8, and the used LED is from LUXEON, L XK2-PW14-U00, with 0.6Ω dynamic resistance)

I_{OUT} , R_{SEN} and D

The R_{SEN} can be calculated by (3), $R_{SEN} = 0.1V / 0.35A = 0.286\Omega$. Here select a 0.3Ω resistor to be R_{SEN} . The sustaining power dissipation is $P_{RSEN} = 0.1V^2 / 0.3\Omega = 0.033W$. Thus, a 1%, 0.3Ω resistor with 0.125W power dissipation is recommended.

Because the R_{SEN} is 0.3Ω, the LED current would be $I_{OUT} = 0.1V / 0.3\Omega = 333mA$.

Since the duty cycle of MBI6651 is $D = (3.72V \times 2) / 12V = 0.62$, the switching frequency should be determined by minimum off time, 350ns; thus the switching frequency is $f_{SW} = 1 / (350ns / (1 - 0.62)) = 1.086MHz$.

Inductor Selection

From (5), the inductor, L1, can be chosen

$$L1 > [12V - (3.72 \times 2) - 0.1V - (0.45\Omega \times 0.333A)] \times [0.62 / (1.086MHz \times 0.3 \times 0.333A)] = 24.63\mu H$$

Thus, the recommended inductor is 33μH with 0.75A saturation current and 0.16Ω DCR. And since the inductor is changed to 33μH, the switching frequency should be modified as

$$f_{SW} = [12V - (3.72 \times 2) - 0.1V - (0.45\Omega \times 0.333A)] \times [0.62 / (33\mu H \times 0.3 \times 0.333A)] = 810.6kHz$$

Schottky Selection

In this application, the recommended selection in the schottky diode is SSCD102 with 20V reverse voltage, 1A forward current, and 0.5V forward voltage as its maximum.

Minimum Input Voltage

The minimum input voltage is the sum of voltage drops on each current carrying element and the forward voltage of LEDs during MOSFET turns on. The voltage drops on each component are

$$V_{RSEN} = 0.1V \times 1.15 = 0.115V$$

$$V_{RS} = 0.6\Omega \times 0.333A \times 1.15 \times 2 = 0.46V$$

$$V_{MOSFET} = 0.45\Omega \times 0.333A \times 1.15 = 0.172V$$

$$V_{L1} = 0.16\Omega \times 0.333A \times 1.15 = 0.061V$$

Thus the minimum input voltage is $V_{IN, MIN} = 0.115V + 0.46V + 0.172V + 0.061V + 7.44 = 8.248V$

Input Capacitor Selection

To handle this system safely, a 10uF tantalum capacitor with 16V rated voltage is recommended.

Bypass Capacitor Selection

To avoid the noise interference, a 0.1uF ceramic capacitor with 16V rated voltage is recommended to be the by pass capacitor.

Output Capacitor Selection

For LED ripple current reduction, an output capacitor parallels with LED array is required. In this example, the recommended output capacitor is a ceramic unit with 10uF and the rated voltage is 10V.

Efficiency

The power consumption on each component can be calculated as

$$P_{OUT} = V_{OUT} \times I_{OUT} = 2 \times 3.72V \times 0.333A = 2.478W$$

$$P_C = I_{OUT}^2 \times R_{ds(on)} \times D = (0.333A)^2 \times 0.45\Omega \times 0.62 = 31mW$$

$$P_{SW} = V_{IN} \times I_{OUT} \times (t_r + t_f) \times f_{SW} = 12V \times 0.333A \times (60ns) \times 810.6kHz = 194mW$$

$$P_{IC} = I_{DD} \times V_{IN} = 1mA \times 12V = 12mW$$

$$P_L = I_{OUT}^2 \times DCR = (0.333A)^2 \times 0.16\Omega = 17.74mW$$

$$P_{D1} = V_{F, D1} \times I_{OUT} \times (1-D) = 0.5V \times 0.333A \times (1-0.62) = 63.27mW$$

$$P_{RSEN} = V_{SEN} \times I_{OUT} = 0.1V \times 0.333A = 33.3mW$$

$$P_{LOSS} = P_C + P_{SW} + P_{IC} + P_L + P_{D1} + P_{RSEN} = 351.31mW$$

Thus, the efficiency in this application is

$$\eta = \frac{P_{OUT}}{P_{OUT} + P_{LOSS}} = \frac{2.478W}{2.478W + 351.31mW} \times 100\% = 87.58\%$$

Raised Junction Temperature

The raised junction temperature can be estimated by

$$T_J = T_A + P_{LOSS, IC} \times R_{th, JA} = 25 + (31mW + 194mW + 12mW) \times 35.53 \text{ } /W = 33.42 \text{ } .$$

Followings show the application circuit and BOM for reference.

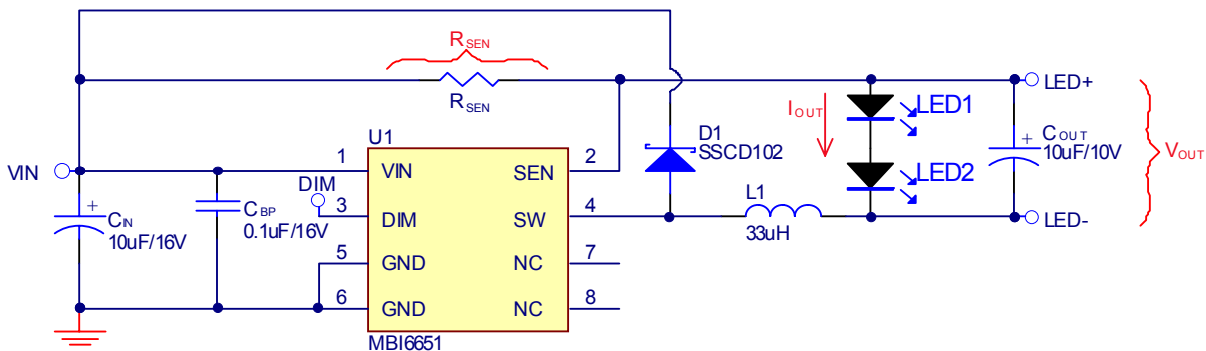


Figure 4 The application circuit of example 1

Table 1 The BOM of example 1

Designator	Part Type	Description	Vendor	Contact Window
C _{IN}	10uF/16V	TAJT106K016R, Tantalum capacitor	AVX	+886-3-594-1818-68
C _{BP}	0.1uF/16V	0805, X7R, EMK212B7104KD-T, Ceramic Capacitor	TAIYO YUDEN	+886-2-2797-2155
C _{OUT}	10uF/10V	TAJA106K010R, Tantalum capacitor	AVX	+886-3-594-1818-68
D1	S5CD102	20V/1A Surface Mount Schottky Barrier Rectifier	ZOEWIE	+886-2-2219-5533-211
L1	33uH	SLF7032T-330MR75-2PF	TDK	+886-3-592-7225
R _{SEN}	0.3Ω	0805, TCS05FTEUR300, SMD Resistor	Viking	+886-3-597-2931-5818
U1	MBI6651GMS	Step-Down, 1A LED Driver, MSOP8	MBI	+886-3-579-0068

Design Example 2

For lighting 3 pieces of high power white LEDs, the forward voltage of LED is 3.72V/pcs. The desired LED current is 1A, input voltage is 24V. Please calculate the required components. (The package of MBI6651 is TO252-5, and the used LED is from LUXEON, LXK2-PW14-U00, with 0.6Ω dynamic resistance)

By the formulas and calculations previous, the parameters and selected components are as bellow

- The duty cycle is $D = (V_{F, LED} \times 3) / V_{IN} = (3.72V \times 3) / 24V = 0.465$
- The switching frequency is $f_{SW} = 1 / (350ns / 0.465) = 1.33MHz$.
- The current sense resistor is $R_{SEN} = V_{SEN} / I_{OUT} = 0.1V / 1A = 0.1\Omega$. Here select a 0.1Ω resistor to be R_{SEN}. And the sustaining power dissipation is $P_{RSEN} = 0.1V^2 / 0.1\Omega = 0.1W$. Thus, the recommended is 1%, 0.1Ω with 0.125W power dissipation.

- The inductor is

$$L1 > (V_{IN} - V_{OUT} - V_{SEN} - (R_{ds(on)} \times I_{OUT})) \times \frac{D}{f_{SW} \times \Delta I_L} = (24V - 11.16V - 0.1V - (0.45\Omega \times 1A)) \times \frac{0.465}{1.33MHz \times 0.3 \times 1A} = 14.34\mu H$$

A 22uH inductor with 1.7A saturation current and 64.3mΩ DCR is recommended. And the modified switching frequency is

$$f_{SW} = (24V - 11.16V - 0.1V - (0.45\Omega \times 1A)) \times \frac{0.465}{22\mu H \times 0.3 \times 1A} = 865.89kHz$$

- In this application, a schottky diode with 40V reverse voltage, 2A forward current, and the maximum forward voltage is 0.5V.
- The minimum input voltage is

$$V_{IN, MIN} = V_{RSEN} + V_{Rs} + V_{MOSFET} + V_{L1} + V_{F, LED}$$

$$= (0.1V \times 1.15) + (0.6 \times 1A \times 1.15 \times 3) + (0.45\Omega \times 1A \times 1.15) + (64.3m\Omega \times 1A \times 1.15) + (3.72V \times 3) = 13.94V$$
- For stabilize system, a 10uF tantalum capacitor with 35V rated voltage is recommended.
- To avoid the noise interference, a 0.1uF ceramic capacitor with 35V rated voltage is recommended to be the by pass capacitor.
- For LED ripple current reduction, an output capacitor parallels with LED array is needed. In this example, the recommended output capacitor is a ceramic unit with 10uF and the rated voltage is 16V.

10. The power consumptions on each component are

$$P_{OUT} = V_{OUT} \times I_{OUT} = 3 \times 3.72V \times 1A = 11.16W$$

$$P_C = I_{OUT}^2 \times R_{ds(on)} \times D = (1A)^2 \times 0.45\Omega \times 0.465 = 209.25mW$$

$$P_{SW} = V_{IN} \times I_{OUT} \times (t_r + t_f) \times f_{SW} = 24V \times 1A \times (60ns) \times 865.89kHz = 1246.88mW$$

$$P_{IC} = I_{DD} \times V_{IN} = 1mA \times 24V = 24mW$$

$$P_L = I_{OUT}^2 \times DCR = (1A)^2 \times 64.3m\Omega = 64.3mW$$

$$P_{D1} = V_{F,D1} \times I_{OUT} \times (1-D) = 0.5V \times 1A \times (1-0.465) = 267.5mW$$

$$P_{RSEN} = V_{SEN} \times I_{OUT} = 0.1V \times 1A = 100mW$$

$$P_{LOSS} = P_C + P_{SW} + P_{IC} + P_L + P_{D1} + P_{RSEN} = 1911.93mW$$

Thus, the efficiency in this application is $\eta = \frac{P_{OUT}}{P_{OUT} + P_{LOSS}} = \frac{11.16W}{11.16W + 1911.93mW} \times 100\% = 85.37\%$

11. The raised junction temperature can be estimated by

$$T_J = T_A + P_{LOSS, IC} \times R_{th, JA} = 25 + (209.25mW + 1246.88mW + 24mW) \times 32.9 \text{ } /W = 73.7 \text{ } .$$

Followings show the application circuit and BOM for reference.

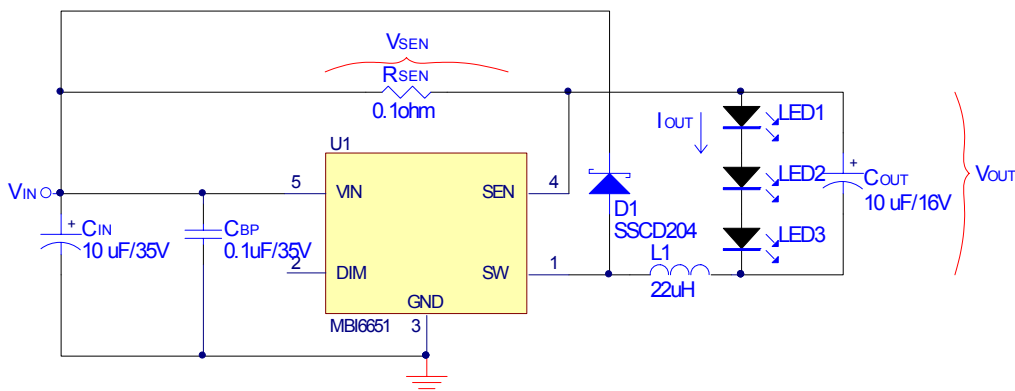


Figure 5 The application circuit of example 2

Table 2 The BOM of example 2

Designator	Part Type	Description	Vendor	Contact Window
C _{IN}	10uF/35V	TAJ106K035R, Tantalum capacitor	AVX	+886-3-594-1818-68
C _{BP}	0.1uF/35V	0805, X7R, GMK212B7104KD-T, Ceramic Capacitor	TAIYO YUDEN	+886-2-2797-2155
C _{OUT}	10uF/16V	TAJT106K016R, Tantalum capacitor	AVX	+886-3-594-1818-68
D1	SSCD204	40V/2A Surface Mount Schottky Barrier Rectifier	ZOEWIE	+886-2-2219-5533-211
L1	22uH	SLF7055T-220M1R7-3PF	TDK	+886-3-592-7225
R _{SEN}	0.1Ω	0805, TCS05FTEUR100, SMD Resistor	Viking	+886-3-597-2931-5818
U1	MBI6651GSD	Step-Down, 1A LED Driver, TO-252-5	MBI	+886-3-579-0068

PCB Layout Consideration

With the aim of enhancing efficiency and stabilizing the system, it is essential to keep a careful printed circuit layout. There are several notes that need to be taken.

1. Keeping a complete ground area is helpful to eliminate the switching noise.
2. Keep the IC's GND pin and the ground leads of input/output filter capacitors in less than 5mm.
3. To maximize the output power, efficiency and minimizing output ripple voltage, use a ground plane and solder the IC's GND pin directly to the ground plane.
4. To stabilize system, the heat sink of MBI6651 is recommended to connect to ground plane directly.
5. To enhance heat dissipation, the area of ground plane, which IC's heat sink is soldered on it, should be as larger as possible.
6. The input and bypass capacitors should be placed to IC's VIN and GND pins as close as possible.
7. To avoid the parasitic effect of trace, the R_{SEN} should be placed to IC's VIN and SEN pins as close as possible.
8. The area, which is comprised by IC's SW pin, schottky diode and inductor, should be wide and short.
9. The path, which flows large current, should be wide and short to eliminate the parasite element.
10. When the SW is on/off, the direction of power loop should keep the same way to enhance the efficiency. The sketch is shown as figure 6.
11. To avoid unexpected damage or malfunction to the driver board, users should pay attention to the quality of soldering in the PCB by checking if cold welding or cold joint happens between the pins of IC and the PCB.

Figure 7 is the recommended layout diagram of MBI6651GSD.

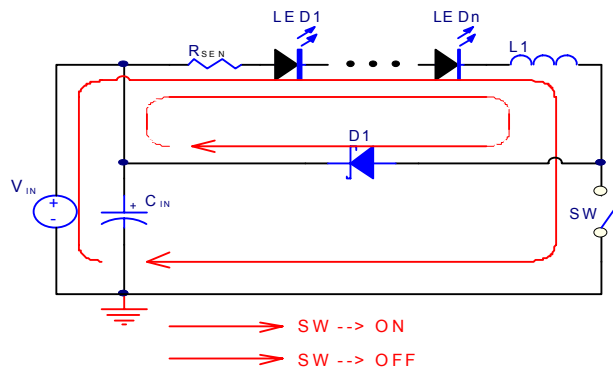


Figure 6 The sketch of power loop

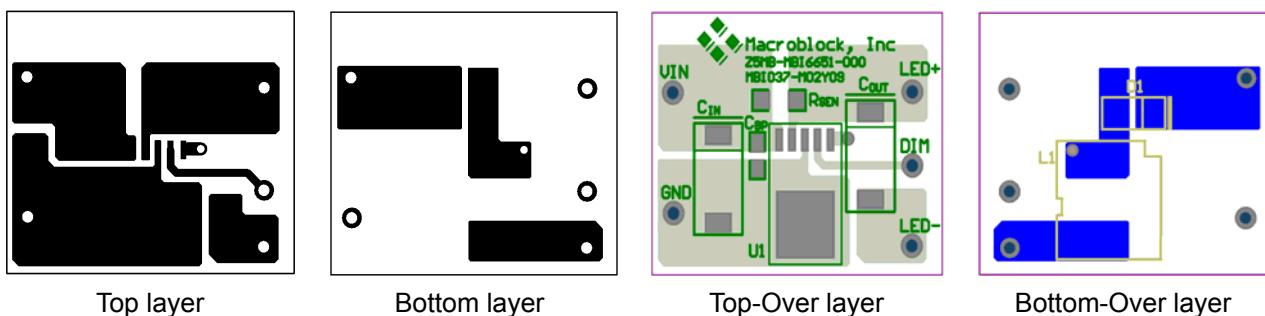


Figure 7. The layout diagram of MBI6651GSD